

# Jihoon Seo

## List of Publications by Year in descending order

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Version: 2024-02-01

38  
papers

752  
citations

623734

14  
h-index

526287

27  
g-index

38  
all docs

38  
docs citations

38  
times ranked

854  
citing authors

#	ARTICLE	IF	CITATIONS
1	Synergistic Ultrathin Functional Polymer-Coated Carbon Nanotube Interlayer for High Performance Lithium-Sulfur Batteries. ACS Applied Materials & Interfaces, 2016, 8, 20092-20099.	8.0	102
2	Synergistic protective effect of a BN-carbon separator for highly stable lithium sulfur batteries. NPG Asia Materials, 2017, 9, e375-e375.	7.9	85
3	Almost Complete Removal of Ceria Particles Down to 10Ånm Size from Silicon Dioxide Surfaces. ECS Journal of Solid State Science and Technology, 2018, 7, P243-P252.	1.8	58
4	A review on chemical and mechanical phenomena at the wafer interface during chemical mechanical planarization. Journal of Materials Research, 2021, 36, 235-257.	2.6	55
5	Role of the Surface Chemistry of Ceria Surfaces on Silicate Adsorption. ACS Applied Materials & Interfaces, 2014, 6, 7388-7394.	8.0	44
6	Ammonium Persulfate and Potassium Oleate Containing Silica Dispersions for Chemical Mechanical Polishing for Cobalt Interconnect Applications. ECS Journal of Solid State Science and Technology, 2019, 8, P3001-P3008.	1.8	44
7	Role of the oxidation state of cerium on the ceria surfaces for silicate adsorption. Applied Surface Science, 2016, 389, 311-315.	6.1	37
8	Two-dimensional Nafion nanoweb anion-shield for improved electrochemical performances of lithium-sulfur batteries. Journal of Materials Chemistry A, 2016, 4, 11203-11206.	10.3	35
9	Post-CMP Cleaning Solutions for the Removal of Organic Contaminants with Reduced Galvanic Corrosion at Copper/Cobalt Interface for Advanced Cu Interconnect Applications. ECS Journal of Solid State Science and Technology, 2019, 8, P379-P387.	1.8	34
10	Multi-objective optimization of tungsten CMP slurry for advanced semiconductor manufacturing using a response surface methodology. Materials and Design, 2017, 117, 131-138.	7.0	30
11	Formation of Cobalt-BTA Complexes and Their Removal from Various Surfaces Relevant to Cobalt Interconnect Applications. ECS Journal of Solid State Science and Technology, 2019, 8, P3009-P3017.	1.8	28
12	Size-dependent interactions of silica nanoparticles with a flat silica surface. Journal of Colloid and Interface Science, 2016, 483, 177-184.	9.4	25
13	Ce <sup>3+</sup> -enriched core-shell ceria nanoparticles for silicate adsorption. Journal of Materials Research, 2017, 32, 2829-2836.	2.6	20
14	Cleaning Solutions for Removal of ~430 nm Ceria Particles from Proline and Citric Acid Containing Slurries Deposited on Silicon Dioxide and Silicon Nitride Surfaces. ECS Journal of Solid State Science and Technology, 2020, 9, 044013.	1.8	20
15	Control of Adhesion Force Between Ceria Particles and Polishing Pad in Shallow Trench Isolation Chemical Mechanical Planarization. Journal of Nanoscience and Nanotechnology, 2014, 14, 4351-4356.	0.9	15
16	Interpolymer complexes of poly(acrylic acid) and poly(ethylene glycol) for low dishing in STI CMP. Applied Surface Science, 2015, 353, 499-503.	6.1	15
17	Preparation and characterization of slurry for chemical mechanical planarization (CMP)., 2016, , 273-298.		15
18	Communication-Synergistic Effect of Mixed Particle Size on W CMP Process: Optimization Using Experimental Design. ECS Journal of Solid State Science and Technology, 2017, 6, P42-P44.	1.8	12

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19	Effects of physico-chemical properties between poly(ethyleneimine) and silica abrasive on copper chemical mechanical planarization. <i>Microelectronic Engineering</i> , 2014, 113, 50-54.	2.4	10
20	Control of Tungsten Protrusion with Surface Active Agent during Tungsten Chemical Mechanical Polishing. <i>ECS Journal of Solid State Science and Technology</i> , 2017, 6, P822-P827.	1.8	8
21	Trajectories, diffusion, and interactions of single ceria particles on a glass surface observed by evanescent wave microscopy. <i>Journal of Materials Research</i> , 2020, 35, 321-331.	2.6	8
22	Communicationâ€”Corrosion Behavior of Tungsten Metal Gate in the Presence of Hydrogen Peroxide at Acidic Medium. <i>ECS Journal of Solid State Science and Technology</i> , 2017, 6, P169-P171.	1.8	7
23	Optimizing a blend of a mixture slurry in chemical mechanical planarization for advanced semiconductor manufacturing using a posterior preference articulation approach to dual response surface optimization. <i>Applied Stochastic Models in Business and Industry</i> , 2016, 32, 648-659.	1.5	5
24	Highly Dispersed Fe <sup>3+</sup> -Substituted Colloidal Silica Nanoparticles for Defect-Free Tungsten Chemical Mechanical Planarization. <i>ECS Journal of Solid State Science and Technology</i> , 2017, 6, P405-P409.	1.8	5
25	Communicationâ€”Reduction of Friction Force between Ceria and SiO <sub>2</sub> for Low Dishing in STI CMP. <i>ECS Journal of Solid State Science and Technology</i> , 2017, 6, P752-P754.	1.8	5
26	Real-Time Visualization of the Cleaning of Ceria Particles from Silicon Dioxide Films Using PVA Brush Scrubbing. <i>ECS Journal of Solid State Science and Technology</i> , 2021, 10, 084004.	1.8	5
27	A review on chemical and mechanical phenomena at the wafer interface during chemical mechanical planarization. <i>Journal of Materials Research</i> , 2021, 36, 1-23.	2.6	5
28	Toward Functional 3D Architected Platform: Advanced Approach to Anchor Functional Metal Oxide onto 3D Printed Scaffold. <i>Advanced Engineering Materials</i> , 2018, 20, 1700901.	3.5	4
29	Environmentally-harmless polylactic acid-polyethylene glycol binder for deformable ceramic green body. <i>Ceramics International</i> , 2018, 44, 4220-4224.	4.8	3
30	Challenges and solutions for post-CMP cleaning at device and interconnect levels. , 2022, , 503-532.		3
31	Suppression of Dissolution Rate via Coordination Complex in Tungsten Chemical Mechanical Planarization. <i>Applied Sciences (Switzerland)</i> , 2022, 12, 1227.	2.5	3
32	3D trajectories and diffusion of single ceria particles near a glass surface and their removal. <i>Journal of Materials Research</i> , 2021, 36, 258-267.	2.6	2
33	Chemical Mechanical Planarization-Related to Contaminants: Their Sources and Characteristics. , 0, , .		2
34	Measurement of the force required to move ceria particles from SiO <sub>2</sub> surfaces using lateral force microscopy. <i>Journal of Materials Research</i> , 2022, 37, 1789-1797.	2.6	2
35	Storage Temperature Effects on the Slurry Health Parameters and SiO <sub>2</sub> Removal Rates during Chemical Mechanical Polishing. <i>ECS Journal of Solid State Science and Technology</i> , 2021, 10, 104002.	1.8	1
36	Direct Observation of Adsorption of Ceria Particles on the Silicon Dioxide Surfaces and Their Removal. <i>ECS Meeting Abstracts</i> , 2021, MA2021-01, 832-832.	0.0	0

#	ARTICLE	IF	CITATIONS
37	Challenges and Solutions for Post-CMP Cleaning of Ceria Particles for Advanced Technology Nodes. ECS Meeting Abstracts, 2021, MA2021-01, 811-811.	0.0	0
38	3D trajectories and diffusion of single ceria particles near a glass surface and their removal. Journal of Materials Research, 2021, 36, 1-10.	2.6	0